MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

SOIC14 N
CASE 751ER
ISSUE O

DATE 31 DEC 2016

DOCUMENT NUMBER: 98AON13761G
STATUS: ON SEMICONDUCTOR STANDARD
NEW STANDARD: ON SEMICONDUCTOR STANDARD
DESCRIPTION: SOIC14 N

NOTES: UNLESS OTHERWISE SPECIFIED
A. THIS PACKAGE REFERENCE TO JEDEC MS-012 VARIATION AB.
B. ALL DIMENSIONS ARE IN MILLIMETERS.
C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH AND TIE BAR EXTRUSIONS.
△ OUT OF JEDEC STANDARD VALUE.

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